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December 9, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |

Thomas Aisenbrey

LOW COST THERMAL MANAGEMENT DEVICE
OR HEAT SINK USING CONDUCTIVE
PLASTICS OR CONDUCTIVE COMPOSITES

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
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mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on December 13, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 12/13/04

U.S. Patent 5,857,767 to Hochstein, "Thermal Management System for L.E.D. Arrays," discloses a method of manufacturing an electrically driven L.E.D. lamp assembly.

U.S. Patent 6,364,009 to MacManus et al., "Cooling Devices," discloses a cooling apparatus for cooling an electrical device using a flow of coolant comprising a cooling unit.

U.S. Patent 5,849,130 to Browne, "Method of Making and Using Thermally Conductive Joining Film," discusses a thermally conductive film that includes a film of polymeric matrix material having a thickness defined between a top surface and a bottom surface.

European Patent Application EP 0 506 509 A to Sono et al., "Semiconductor Device Having Radiation Part and Method of Producing the Same," discloses a semiconductor device having a radiation part for radiating heat and a method of producing such a semiconductor device.

International Patent Application WO 03/017365 A to Flint et al., "Thermal Transfer Devices," discusses thermal transfer devices, including heat pipes and vapor chambers.

U.S. Patent 6,397,941 to McCullough, "Net-Shape Molded Heat Exchanger," discloses a net-shape molded heat exchanger which includes a thermally conductive main body and a number of thermally conductive arms connected to and extending from the main body.

European Patent Application EP 1 265 281 A to Tobita et al., "Thermally Conductive Molded Article and Method of Making the Same," discloses a thermally conductive molded article that has excellent thermal conductivity and a method of making the same.

International Patent Application WO 95/09444 to Moore, "LED Assembly with Enhanced Power Output," discloses a light emitting diode (LED) assembly which is designed for use in a remote control and which has enhanced power output.

U.S. Patent Application Publication US 2002/0178621 to Song et al., "Light Emitting Diode, Light Emitting Device Using the Same, and Fabrication Processes Therefor," discloses a LED which can be mounted at high density on a large area display.

U.S. Patent Application Publication US 2002/0072137 to Ih, "Optosemiconductor Device and the Method for Its Manufacture," discloses an optosemiconductor device, improved in light-emission efficiency and heat-radiation capability.

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)				Document Number (Optional) INT-03-008	Application Number 10/807,036	
				Applicant Thomas Aisenbrey		
				Filing Date 03/23/04	Group Art Unit	
U.S. TRADEMARK						
PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	PLACED DATE IF APPROPRIATE
	5 857767	1/12/99	Hochstein	362	294	2/25/97
	6 364009	4/2/02	MacManus et al.	165	185	1/26/00
	5 849130	12/15/98	Browne	156	256	6/12/97
	6 397941	6/4/02	McCullough	165	185	11/7/00
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	EP 0506509 A2	3/16/92	European Patent App.	H01L	23/055	
	WO 03/017365 A2	8/17/01	Int'l Patent App.	H01L	23/34	
	EP 1 265281 A2	6/5/02	European Patent App.	H01L	23/373	
	WO 95/094444 A	9/28/94	Int'l Patent App.	H01L	33/00	
OTHER DOCUMENTS (Including Author, Title, Date, Page, Etc.)						
-	US Patent App. Pub. US 2002/0175621 A1 to Song et al., Filed 10/19/01, Pub. Date 11/28/02, US Cl. 313/515.					
-	US Patent App. Pub. US 2002/0072137 A1 to Ih, Filed 03/05/01, Pub. Date 06/13/02, US Cl. 438/22.					
-	US Patent App. Pub. US 2001/0050441 A1 to Shrivkumar et al., Filed 03/19/01, Pub. Date 12/13/01, US Cl. 257/778.					
EXAMINER				DATE CONSIDERED		

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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